74LVTH16373
3.3V, 16-Bit D-Type Transparent Latch with 3-State Outputs

GENERAL DESCRIPTION

The 74LVTH16373 is a 16-bit D-type transparent latch with non-inverting 3-state outputs which is designed for 3.3V supply voltage. The device can provide capability in driving highly capacitive or relatively low-impedance loads, which makes it especially suitable for use in implementing buffer registers, I/O ports, bidirectional bus drivers and working registers.

The device can operate as two 8-bit latches or one 16-bit latch. When latch enable input nLE is set high, the outputs nQn will appear the data of inputs nDn. When nLE is set low, the nQn outputs will be latched at the levels of the inputs nDn one set-up time preceding the high-to-low transition.

A buffered output enable $n\overline{OE}$ input can make the 8 outputs set to either high/low logic levels or high-impedance state.

The bus hold on data inputs makes it unnecessary to use external pull-up/pull-down resistors to hold unused input.

FEATURES

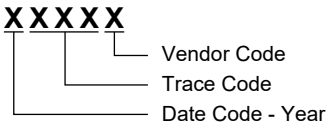
- **Wide Operating Voltage Range: 3.3V**
- **Input and Output Interface Capability to 5V System Environment**
- **+64mA/-32mA Output Current**
- **16-Bit Transparent Latch**
- **3-State Buffers**
- **Input and Output Switching Levels of TTL**
- **Power-up Reset**
- **Power-up 3-State**
- **No Bus Current Loading when Output is Connected to 5V Bus**
- **No External Pull-up/Pull-down Resistors are Required Due to the Bus Hold on Data Inputs**
- **Support Live Insertion and Extraction**
- **-40℃ to +125℃ Operating Temperature Range**
- **Available in a Green TSSOP-48 Package**

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
74LVTH16373	TSSOP-48	-40℃ to +125℃	74LVTH16373XTS48G/TR	74LVTH16373 XTS48 XXXXX	Tape and Reel, 2500

MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code.



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS (1)

Supply Voltage, V_{CC} ..... -0.5V to 4.6V
Input Voltage, V_I (2) ..... -0.5V to 7V
Output Voltage, V_O (2)
High-Impedance State ..... -0.5V to 7V
High-State or Low-State..... -0.5V to MIN (7V, V_{CC} + 0.5V)
Input Clamping Current, I_{IK} (V_I < 0V) .....-50mA
Output Clamping Current, I_{OK} (V_O < 0V).....-50mA
Output Current, I_O
High-State .....-64mA
Low-State.....128mA
Supply Current, I_{CC} 128mA
Ground Current, I_{GND}.....-256mA
Junction Temperature (3) .....+150℃
Storage Temperature Range .....-65℃ to +150℃
Lead Temperature (Soldering, 10s).....+260℃
ESD Susceptibility
HBM.....7000V
CDM 1000V

RECOMMENDED OPERATING CONDITIONS

Supply Voltage, V_{CC}.....2.7V to 3.6V
Input Voltage, V_I.....0V to 5.5V
Output Voltage, V_O
High-Impedance State .....0V to 5.5V
High-State or Low-State..... 0V to V_{CC}
High-Level Output Current, I_{OH} .....-32mA
Low-Level Output Current, I_{OL}.....64mA
Input Transition Rise and Fall Rate, Δt/ΔV
..... 10ns/V (MAX)
Operating Temperature Range.....-40℃ to +125℃

OVERSTRESS CAUTION

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

2. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

3. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

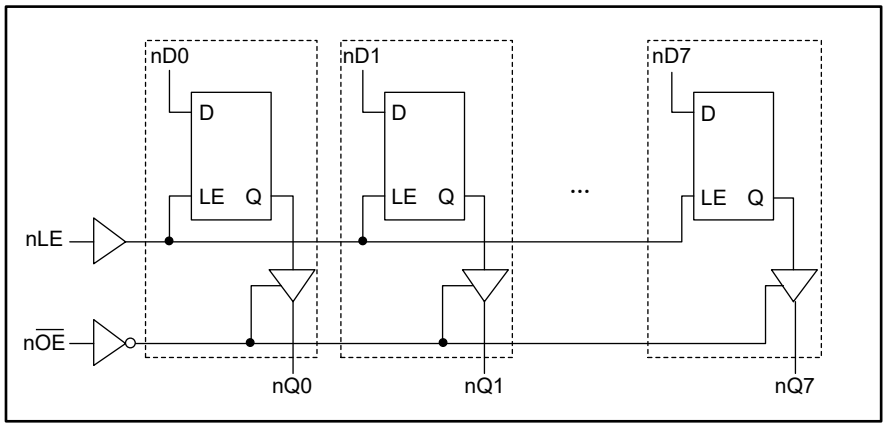
ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

LOGIC DIAGRAM



FUNCTION TABLE

CONTROL INPUT			INTERNAL REGISTER	OUTPUT
$n\overline{OE}$	nLE	nDn		nQn
L	H	L	L	L
L	H	H	H	H
L	L	l	L	L
L	L	h	H	H
H	L	l	L	Z
H	L	h	H	Z

H = High Voltage Level

L = Low Voltage Level

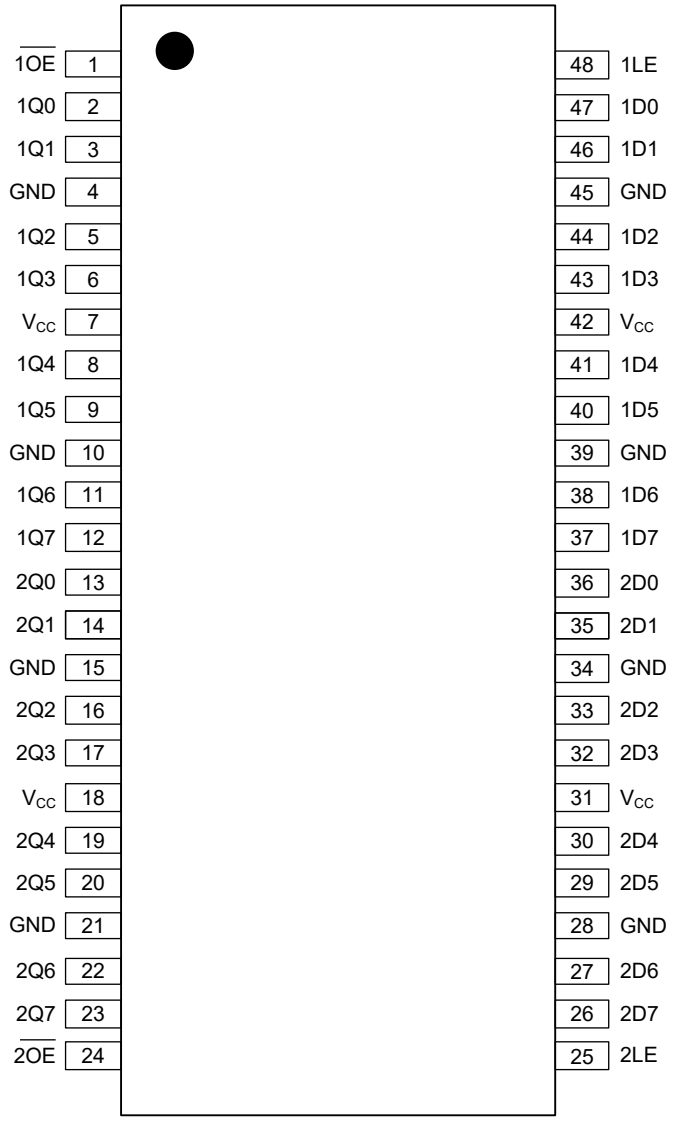
h = High Voltage Level One Set-Up Time Prior to the High-to-Low LE Transition

l = Low Voltage Level One Set-Up Time Prior to the High-to-Low LE Transition

Z = High-Impedance State

PIN CONFIGURATION

(TOP VIEW)



TSSOP-48

PIN DESCRIPTION

PIN	NAME	FUNCTION
47, 46, 44, 43, 41, 40, 38, 37	1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7	Data Inputs.
36, 35, 33, 32, 30, 29, 27, 26	2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7	Data Inputs.
1, 24	1$\overline{OE}$, 2$\overline{OE}$	Output Enable Inputs (Active Low).
48, 25	1LE, 2LE	Latch Enable Inputs (Active High).
2, 3, 5, 6, 8, 9, 11, 12	1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7	Data Outputs.
13, 14, 16, 17, 19, 20, 22, 23	2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7	Data Outputs.
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground.
7, 18, 31, 42	V_{CC}	Supply Voltage.

ELECTRICAL CHARACTERISTICS

(Full = -40℃ to +125℃, all typical values are measured at V_{CC} = 3.3V and T_A = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN	TYP	MAX	UNITS
Input Clamping Voltage	V_{IK}	V_{CC} = 2.7V, I_{IK} = -18mA		Full	-1.2	-0.78		V
High-Level Input Voltage	V_{IH}	V_{CC} = 2.7V to 3.6V		Full	2			V
Low-Level Input Voltage	V_{IL}	V_{CC} = 2.7V to 3.6V		Full			0.8	V
High-Level Output Voltage	V_{OH}	I_{OH} = -100μA, V_{CC} = 2.7V to 3.6V		Full	V_{CC} - 0.05	V_{CC} - 0.001		V
		I_{OH} = -8mA, V_{CC} = 2.7V		Full	2.45	2.6		
		I_{OH} = -32mA, V_{CC} = 3.0V		Full	2.1	2.65		
Low-Level Output Voltage	V_{OL}	V_{CC} = 2.7V	I_{OL} = 100μA	Full		0.001	0.05	V
			I_{OL} = 24mA	Full		0.15	0.28	
		V_{CC} = 3.0V	I_{OL} = 16mA	Full		0.1	0.18	
			I_{OL} = 32mA	Full		0.2	0.36	
			I_{OL} = 64mA	Full		0.4	0.55	
Power-Up Low-Level Output Voltage (1)	V_{OL_PU}	V_{CC} = 3.6V, I_{OL} = 1mA, V_I = V_{CC} or GND		Full		5	50	mV
Input Leakage Current	I_I	Control pins, V_{CC} = 3.6V, V_I = V_{CC} or GND		Full		±0.01	±1	μA
		Control pins, V_{CC} = 0V or 3.6V, V_I = 5.5V		Full		0.01	5	
		Input data pins (2), V_{CC} = 0V or 3.6V, V_I = 5.5V		Full		0.4	5	
		Input data pins (2), V_{CC} = 3.6V, V_I = V_{CC}		Full		0.3	2	
		Input data pins (2), V_{CC} = 3.6V, V_I = GND		Full	-2	-0.01		
Off-State Output Current	I_{OZ}	V_{CC} = 3.6V	V_O = 3.0V	Full		0.01	2	μA
			V_O = 0.5V	Full	-2	-0.01		
Output Leakage Current	I_{LO}	Output in high-state when V_O > V_{CC}, V_O = 5.5V, V_{CC} = 3.0V		Full		1	30	μA
Power-Up/Down Output Current	$I_{O\_PU/PD}$	V_{CC} ≤ 1.2V, V_O = 0.5V to V_{CC}, V_I = GND or V_{CC}, $n\overline{OE}$ = don't care		+25℃		0.01	10	μA
Power-Off Leakage Current	I_{OFF}	V_{CC} = 0V, V_I or V_O = 0V to 5.5V		Full		0.01	10	μA
Supply Current	I_{CC}	V_{CC} = 3.6V, V_I = GND or V_{CC}, I_O = 0A	Outputs high	Full		12	80	μA
			Outputs low	Full		12	80	
			Outputs disabled (3)	Full		12	80	
Additional Supply Current (4)	ΔI_{CC}	Per input pin, V_{CC} = 3.0V to 3.6V, one input at V_{CC} - 0.6V, other inputs at V_{CC} or GND		Full		0.2	200	μA
Input Capacitance	C_I	Input pins, V_I = 0V or 3.0V		+25℃		6		pF
Output Capacitance	C_O	Output pins nQn, outputs disabled, V_O = 0V or V_{CC}		+25℃		9		pF
Bus Hold Low Current	I_{BHL}	V_{CC} = 3.0V, V_I = 0.8V		Full	50	100		μA
Bus Hold High Current	I_{BHH}	V_{CC} = 3.0V, V_I = 2.0V		Full		-130	-75	μA
Bus Hold Low Overdrive Current (5)	I_{BHLO}	Input data pins, V_I = 0V to 3.6V, V_{CC} = 3.6V		Full	500	200		μA
Bus Hold High Overdrive Current (5)	I_{BHHO}	Input data pins, V_I = 0V to 3.6V, V_{CC} = 3.6V		Full		-280	-500	μA

NOTES:

1. The data must not be loaded into the latches after applying power to get valid test results.
2. Other pins must be tied to V_{CC} or GND and should not be floating.
3. I_{CC} is measured with outputs pulled to V_{CC} or GND.
4. It is the increase in supply current for per input at the specified voltage level except V_{CC} or GND.
5. It is the minimum overdrive current required to switch the input from one state to another.

DYNAMIC CHARACTERISTICS

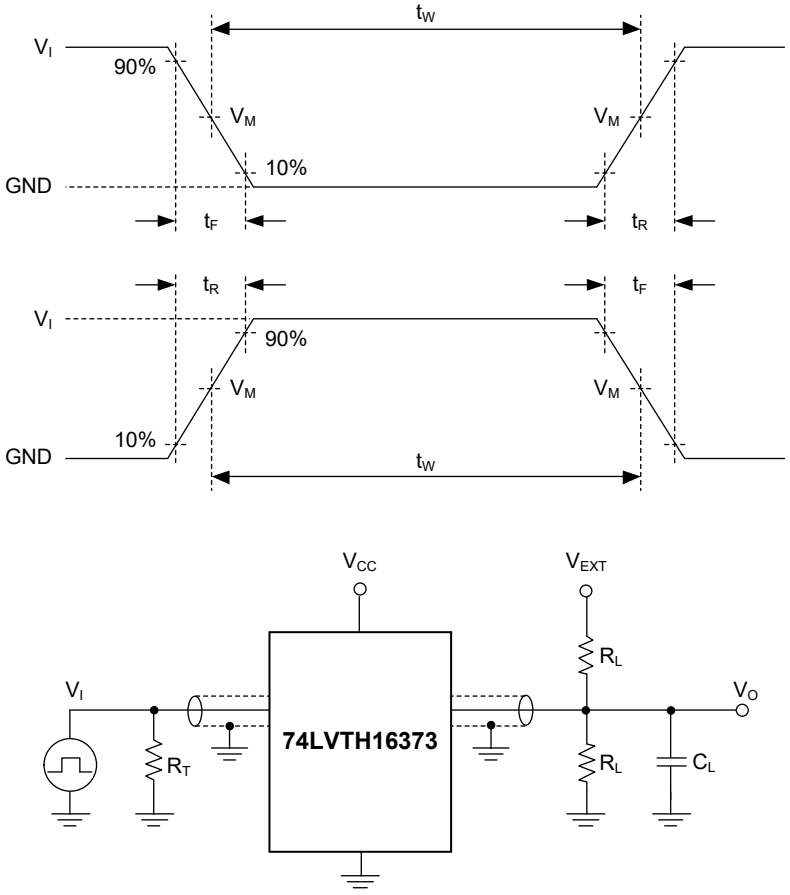
(For test circuit, see Figure 1. All typical values are measured at V_{CC} = 3.3V and T_A = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN (1)	TYP	MAX (1)	UNITS
Low to High Propagation Delay	t_{PLH}	nDn to nQn, see Figure 2	V_{CC} = 2.7V	+25℃		3.6	8.5	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	3.4	7.2	
High to Low Propagation Delay	t_{PHL}	nDn to nQn, see Figure 2	V_{CC} = 2.7V	+25℃		3.2	6.2	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	3.0	5.6	
Low to High Propagation Delay	t_{PLH}	nLE to nQn, see Figure 3	V_{CC} = 2.7V	+25℃		3.8	8.8	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	3.6	7.5	
High to Low Propagation Delay	t_{PHL}	nLE to nQn, see Figure 3	V_{CC} = 2.7V	+25℃		3.4	6.0	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	3.2	5.8	
Off-State to High Propagation Delay	t_{PZH}	$n\overline{OE}$ to nQn, see Figure 4	V_{CC} = 2.7V	+25℃		4.2	9.4	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	4.0	7.8	
Off-State to Low Propagation Delay	t_{PZL}	$n\overline{OE}$ to nQn, see Figure 4	V_{CC} = 2.7V	+25℃		4.0	6.5	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	3.8	6.2	
High to Off-State Propagation Delay	t_{PHZ}	$n\overline{OE}$ to nQn, see Figure 4	V_{CC} = 2.7V	+25℃		4.4	7.6	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	4.0	7.0	
Low to Off-State Propagation Delay	t_{PLZ}	$n\overline{OE}$ to nQn, see Figure 4	V_{CC} = 2.7V	+25℃		4.2	6.8	ns
			V_{CC} = 3.0V to 3.6V	+25℃	0.5	4.0	6.5	
High Set-Up Time	t_{SUH}	nDn to nLE, see Figure 5	V_{CC} = 2.7V	+25℃	2			ns
			V_{CC} = 3.0V to 3.6V	+25℃	2			
Low Set-Up Time	t_{SUL}	nDn to nLE, see Figure 5	V_{CC} = 2.7V	+25℃	2			ns
			V_{CC} = 3.0V to 3.6V	+25℃	2			
High Hold Time	t_{HH}	nDn to nLE, see Figure 5	V_{CC} = 2.7V	+25℃	1.2			ns
			V_{CC} = 3.0V to 3.6V	+25℃	1.2			
Low Hold Time	t_{HL}	nDn to nLE, see Figure 5	V_{CC} = 2.7V	+25℃	1.2			ns
			V_{CC} = 3.0V to 3.6V	+25℃	1.2			
High Pulse Width	t_{WH}	nLE, see Figure 3	V_{CC} = 2.7V	+25℃	3.3			ns
			V_{CC} = 3.0V to 3.6V	+25℃	3.3			

NOTE:

1. Specified by design and characterization; not production tested.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions for test circuit:

R_L: Load resistance.

C_L: Load capacitance (includes jig and probe).

R_T: Termination resistance (equals to output impedance Z_O of the pulse generator).

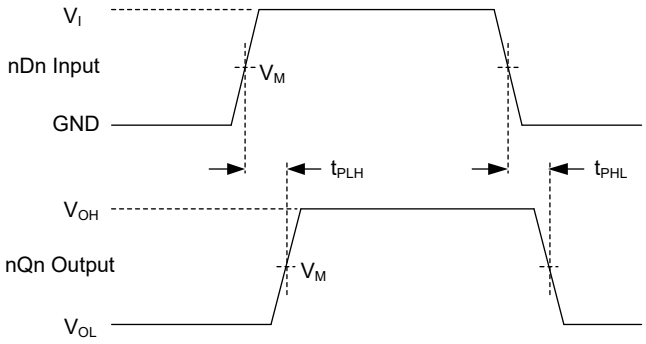
V_{EXT}: External voltage used to measure switching time.

Figure 1. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

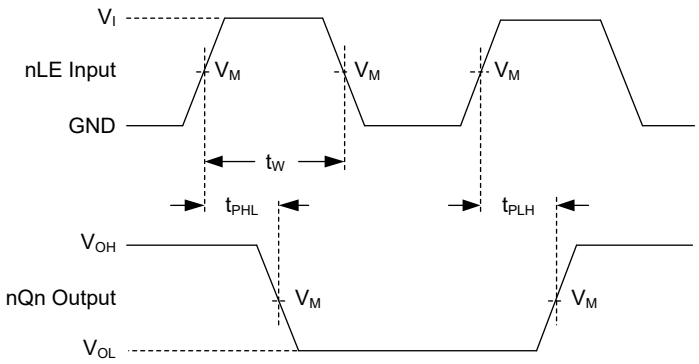
SUPPLY VOLTAGE	INPUT				LOAD		V_{EXT}		
V_{CC}	V_I	f_I	t_W	t_R, t_F	C_L	R_L	t_{PHZ}, t_{PZH}	t_{PLZ}, t_{PZL}	t_{PLH}, t_{PHL}
2.7V to 3.6V	2.7V	≤ 10MHz	500ns	≤ 2.5ns	50pF	500Ω	GND	6V	Open

WAVEFORMS



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

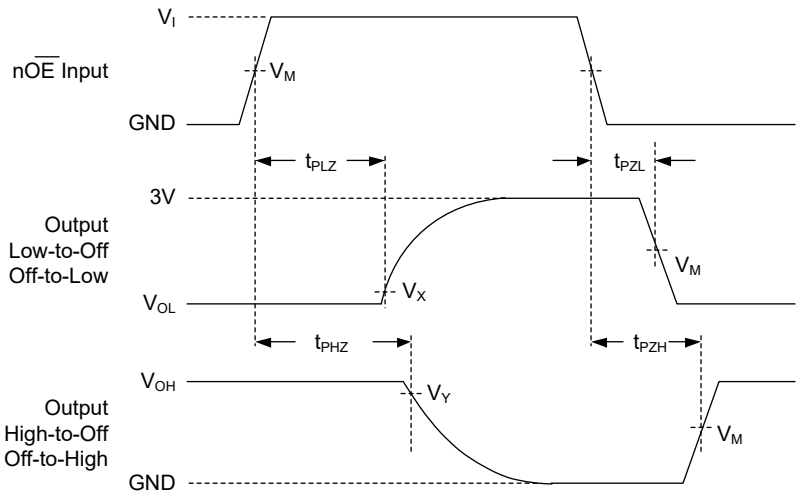
Figure 2. Input (nDn) to Output (nQn) Propagation Delays



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

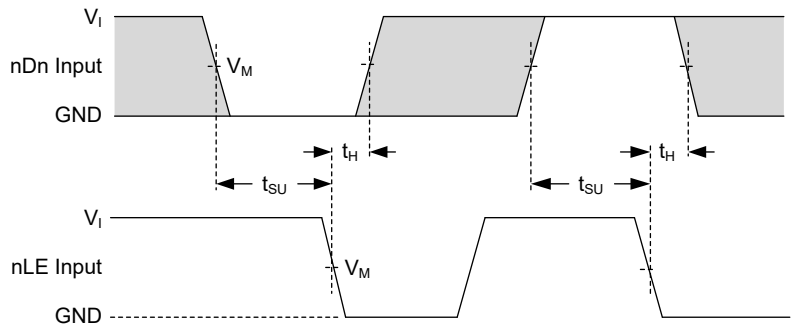
Figure 3. Latch Enable Input Pulse Width and the Latch Enable Input to Output Propagation Delays

WAVEFORMS (continued)



Test conditions are given in Table 1.
Measurement points are given in Table 2.
Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 4. Enable and Disable Times



Test conditions are given in Table 1.
Measurement points are given in Table 2.
The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 5. Data Set-Up and Hold Times for the nDn Input to the nLE Input

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT		
V_{CC}	V_I	V_M (1)	V_M	V_X	V_Y
2.7V to 3.6V	2.7V	1.5V	1.5V	V_{OL} + 0.3V	V_{OH} - 0.3V

NOTE:
1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 2.5ns.

REVISION HISTORY

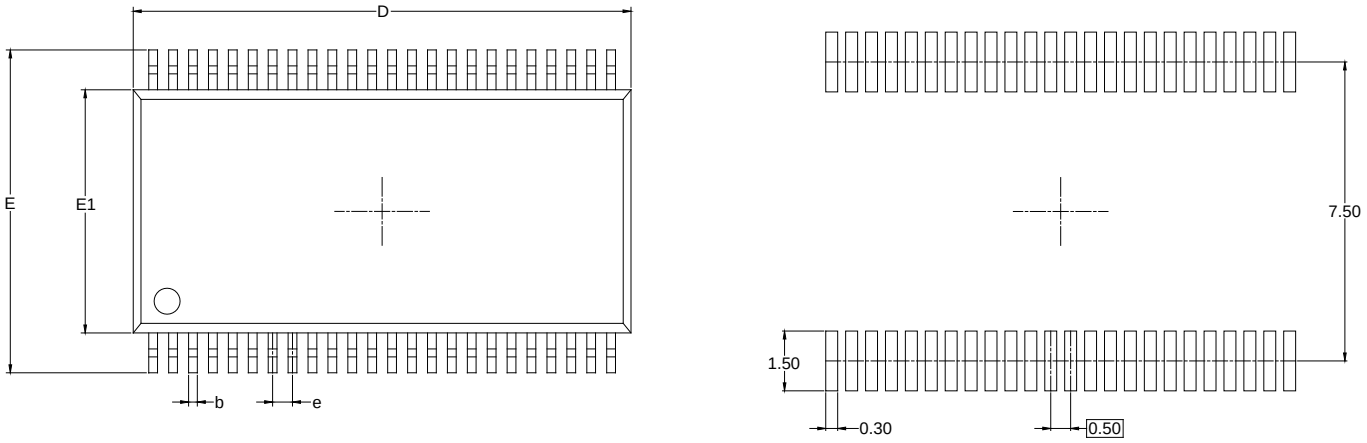
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

NOVEMBER 2021 – REV.A to REV.A.1	Page
Updated HBM value in Absolute Maximum Ratings section	2

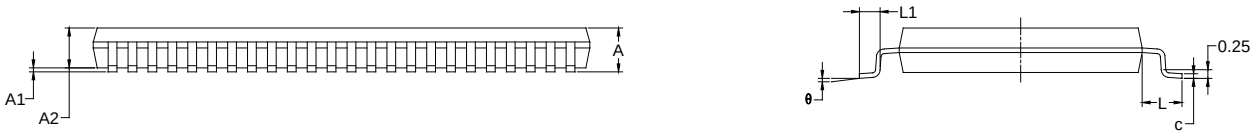
Changes from Original (MARCH 2021) to REV.A	Page
Changed from product preview to production data	All

PACKAGE OUTLINE DIMENSIONS

TSSOP-48



RECOMMENDED LAND PATTERN (Unit: mm)

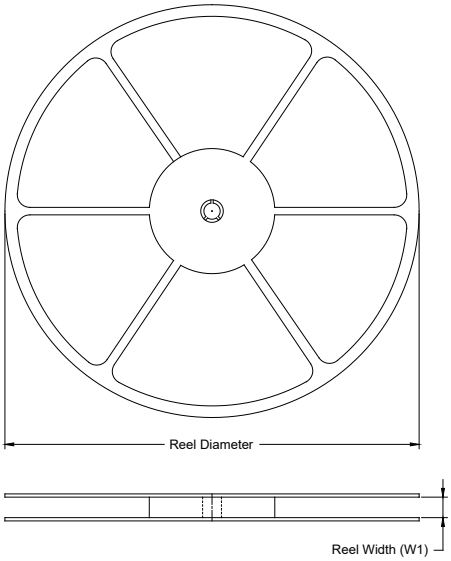


Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A			1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.18		0.26
c	0.15		0.19
D	12.40	12.50	12.60
E	7.90	8.10	8.30
E1	6.00	6.10	6.20
e	0.50 BSC		
L	1.00 REF		
L1	0.45		0.75
θ	0°		8°

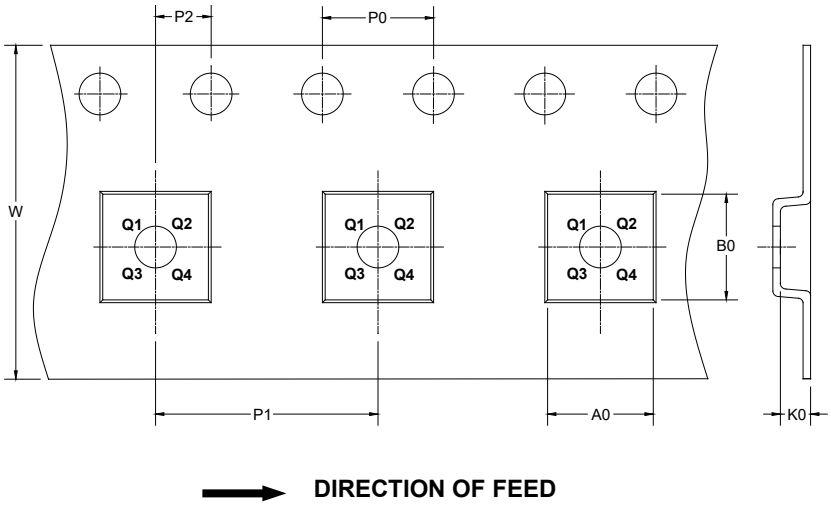
NOTES:
1. Body dimensions do not include mode flash or protrusion.
2. This drawing is subject to change without notice.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



DIRECTION OF FEED

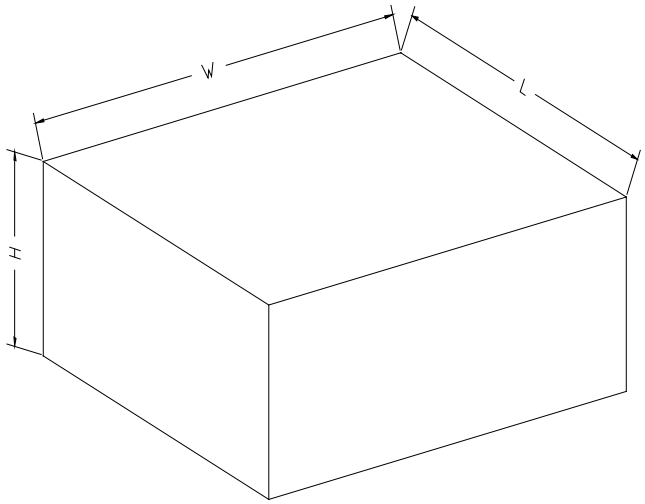
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-48	13”	24.4	8.60	13.00	1.80	4.0	12.0	2.0	24.0	Q1

DD0001

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13″	386	280	370	5

DD0002